

## CHIP-MOUNTED CONTACT SPRINGS

### ABSTRACT OF THE DISCLOSURE

5        Bonding wire is formed into an inverted "V" shape by bonding both ends of a bonding  
wire to adjacent points on an integrated circuit, the vertex of the "V" shape forming a contact  
point for contacting another integrated circuit, or other device. One end of the bonding wire is  
bonded to a specified point on the integrated circuit, the bonding head is raised, and then  
lowered to an immediately adjacent point to effect the second bonding, thus forming the inverted  
10      V shape. This V shape, being bonded at both ends, is mechanically stable, is resilient in form,  
and allows for the use of resilient, or non-resilient bonding wire. The vertex of the V shape  
forms a point or surface for contacting another integrated circuit, or other device, for  
communicating signals to and from the device to which the bonding wire is bonded.

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